

**CX-02GY (RAL-7035)**

PC

Next Polymers Ltd.

Processing/Physical Characteristics	Value	Unit	Test Standard
<b>ASTM Data</b>			
Melt Flow Index, MFI	30	g/10min	ASTM D 1238
Temperature	300	°C	-
Load	1.2	kg	-
Mold Shrinkage, MD	0.004	mm/mm	ASTM D 955
Mold Shrinkage, TD	0.004	mm/mm	ASTM D 955

Mechanical properties	Value	Unit	Test Standard
<b>ASTM Data</b>			
Tensile Modulus	2400	MPa	ASTM D 638
Tensile Strength	60	MPa	ASTM D 638
Elongation at Break	25	%	ASTM D 638
Flexural Modulus	2200	MPa	ASTM D 790
Flexural Strength	95	MPa	ASTM D 790
Rockwell Hardness	R 120	-	ASTM D 785
Izod Impact notched, 1/8 in	706	J/m	ASTM D 256
Izod Impact notched, Low-Temperature	108	J/m	ASTM D 256
Temperature	-30	°C	-

Thermal properties	Value	Unit	Test Standard
<b>ASTM Data</b>			
UL 94 Flame rating	V-2	-	UL 94
Thickness tested	0.8	mm	-
Coefficient of Thermal Expansion, MD	70	E-6/K	ASTM D 696
DTUL @ 66 psi	140	°C	ASTM D 648
DTUL @ 264 psi	124	°C	ASTM D 648
Vicat Temperature	142	°C	ASTM D 1525
Thermal Conductivity, solid state	0.0288	W/(m K)	ASTM C 177

Electrical properties	Value	Unit	Test Standard
<b>ISO Data</b>			
Volume resistivity	1E11	Ohm*m	IEC 62631-3-1
Surface resistivity	1E15	Ohm	IEC 62631-3-2
Electric strength	30	kV/mm	IEC 60243-1
<b>ASTM Data</b>			
Dielectric Constant, 60 Hz	3	-	ASTM D 150

Other properties	Value	Unit	Test Standard
Water Absorption, 24hr	0.3	%	ASTM D 570
Water Absorption, Equilibrium	0.35	%	ASTM D 570
Density	1220	kg/m <sup>3</sup>	ASTM D 792

**Characteristics****Processing**

Injection Molding

**Special Characteristics**

Heat stabilized or stable to heat

**Applications**

Electrical and Electronical, Encapsulation

**Regional Availability**

Asia Pacific